

Intel technologies, tools and techniques for power and energy efficiency analysis

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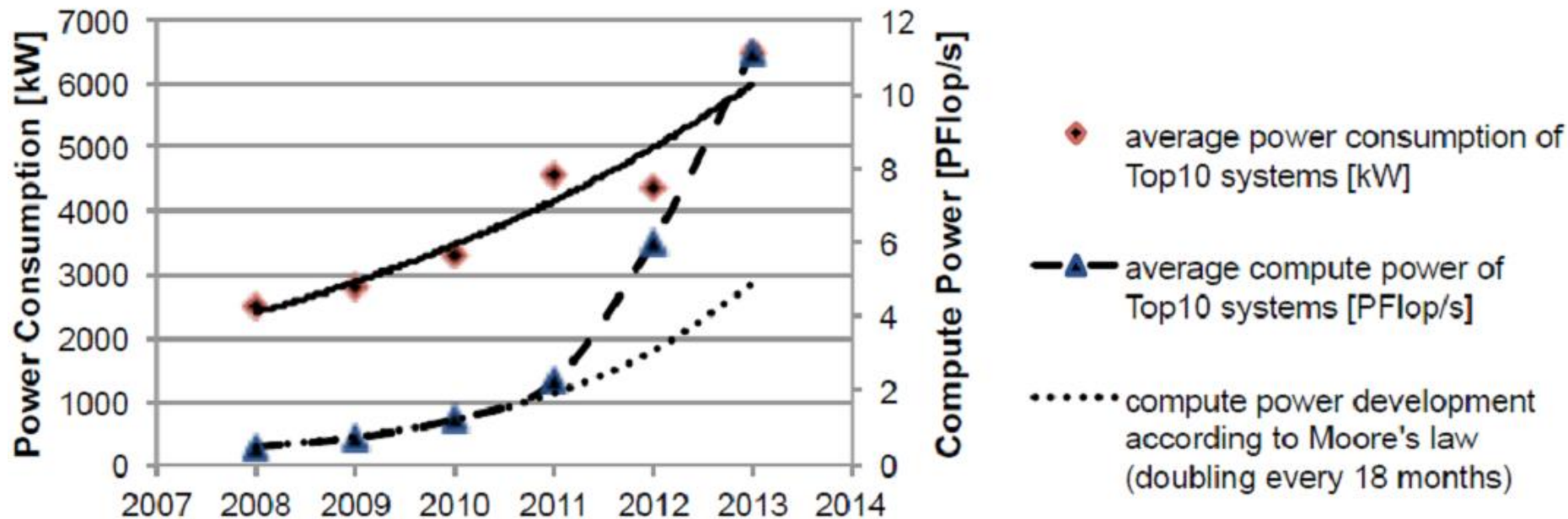
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Agenda

- Power and energy efficiency metrics for datacentres
- Intel tools and techniques for server power monitoring
- Energy monitoring with Intel tools example

Average power and performance of Top10 supercomputers

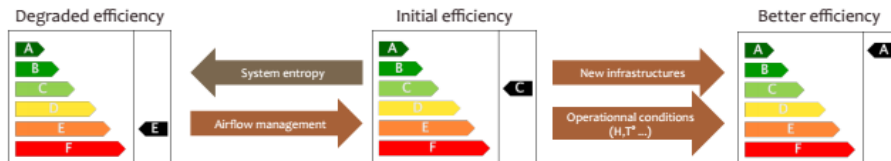


Performance and power of large HPC systems grows faster than Moore's law

Power and energy efficiency

What is power/energy efficiency of application and datacentre?

- PUE, Green500, etc.

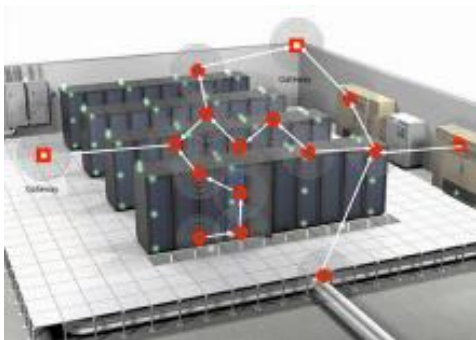


Why care?

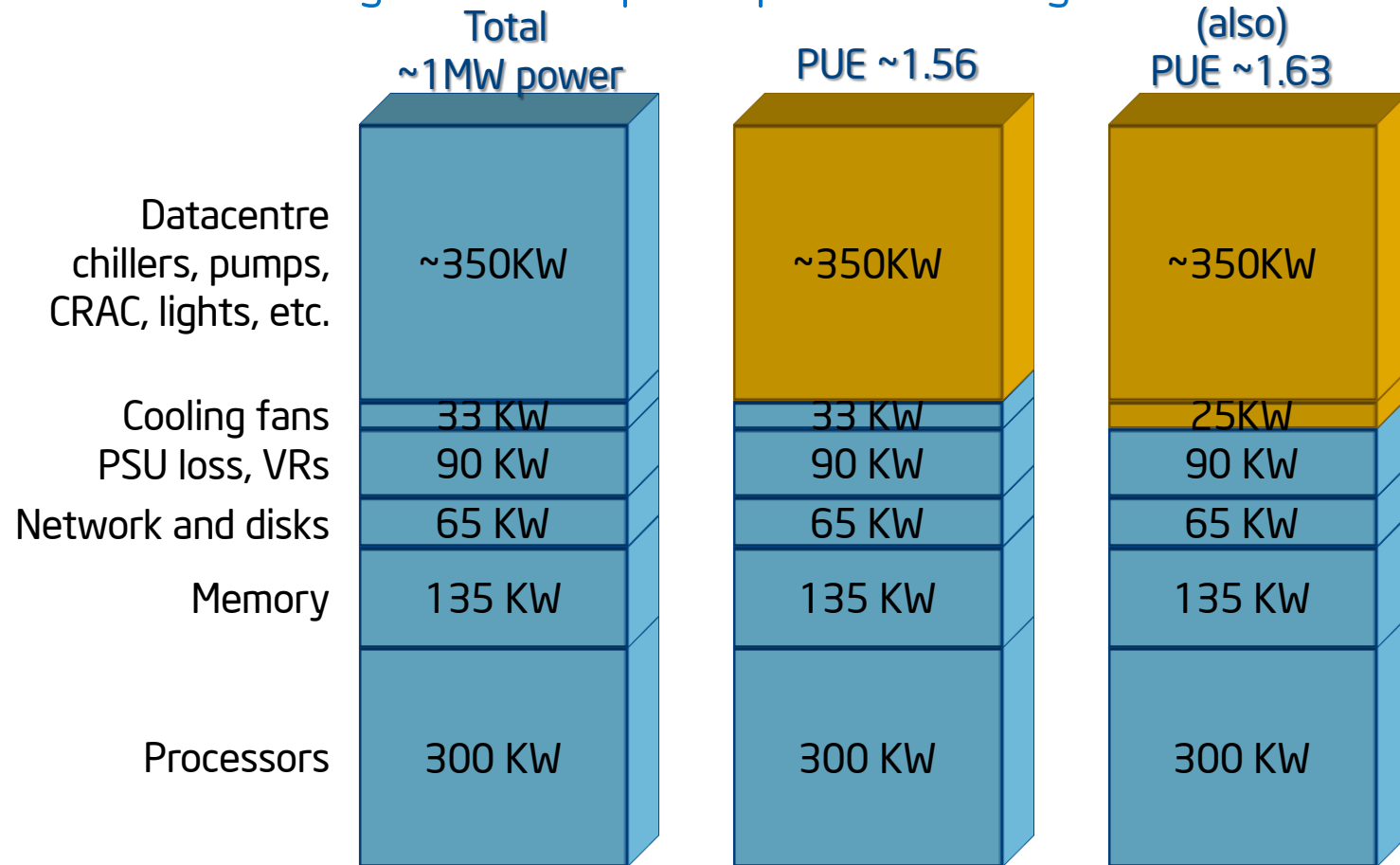
- Can measure => can improve

How to routinely measure?

- Need tools, techniques, etc.



Understanding datacentre power profile and usage effectiveness metrics: PUE



Source: own estimates for 1300 node HPC cluster in 2013. See backup for more details.

Improved approach: introduce ITUE and TUE

Dr. Michael Patterson (Intel) and EEHPCWG Propose a New Metric

ISC13 Gauss Award Winner – Most Outstanding Paper: TUE, a new energy-efficiency metric applied at ORNL's Jaguar

1. **Introduce ITUE:** ITUE is a “PUE-type” metric for the IT equipment
2. **Introduce TUE** - a proposed new metric that uses ITUE and PUE

TUE is a calculated value:

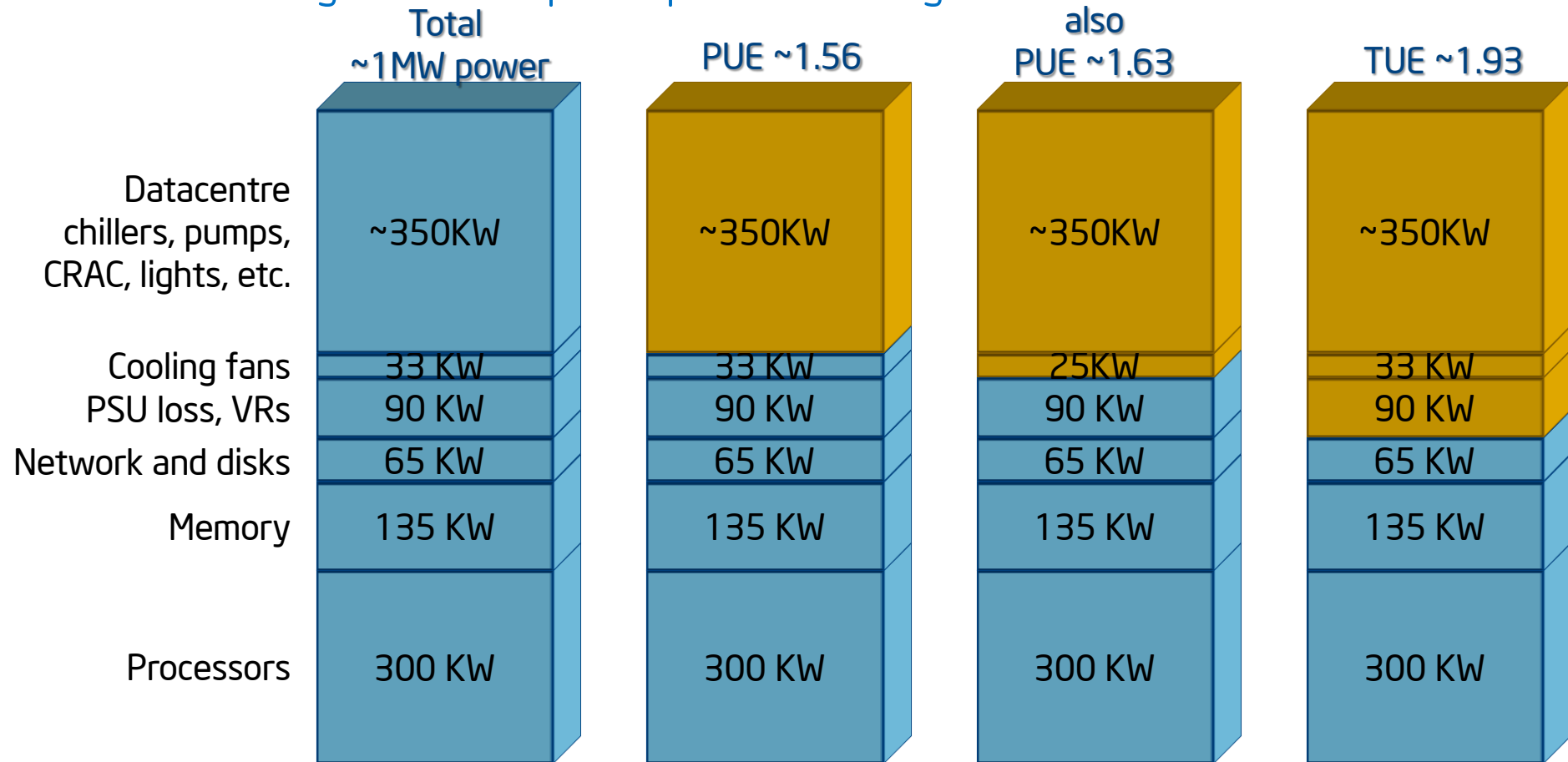
$$TUE = PUE \times ITUE$$

$$ITUE = \frac{\text{Total Energy into the IT equipment (productive + infrastructure)}}{\text{Total Energy into the Compute Components (productive)}}$$

“Productive” components = CPUs, Memory, Storage, Networking

“Infrastructure” = Power Supplies, Voltage Regulators, Fans

Understanding datacentre power profile and usage effectiveness metrics: TUE



Source: own estimates for 1300 node HPC cluster in 2013. See backup for more details.

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Tools and techniques to measure ITUE

$$ITUE = \frac{\textit{Total Energy into the IT equipment (productive + infrastructure)}}{\textit{Total Energy into the Compute Components (productive)}}$$

1. Measure Energy into Compute Components:

E.g. power into CPUs, memory, disks, network switches and integrate over time, such as

$$\textit{Energy}(T) = \int_{t_0}^{t_0+T} \textit{Power}(t)dt$$

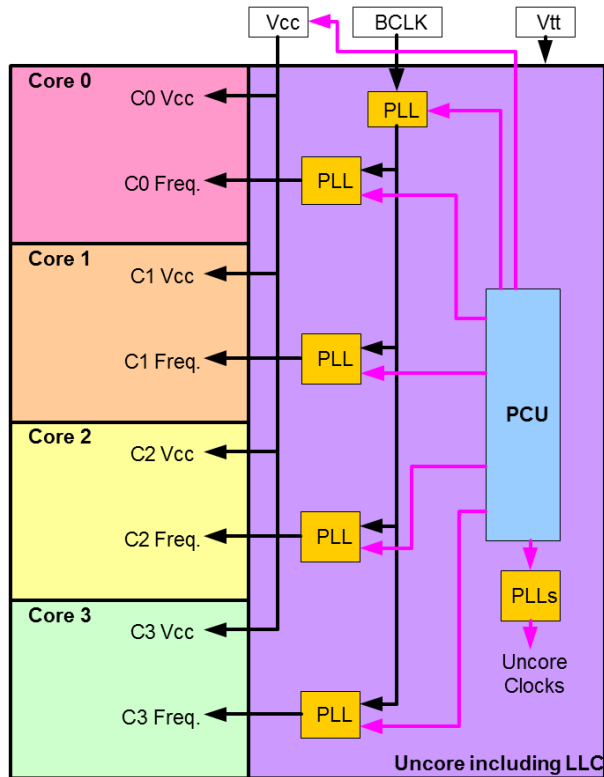
2. Measure Energy into IT Equipment:

E.g. AC power for servers, switch systems, storage arrays and integrate over

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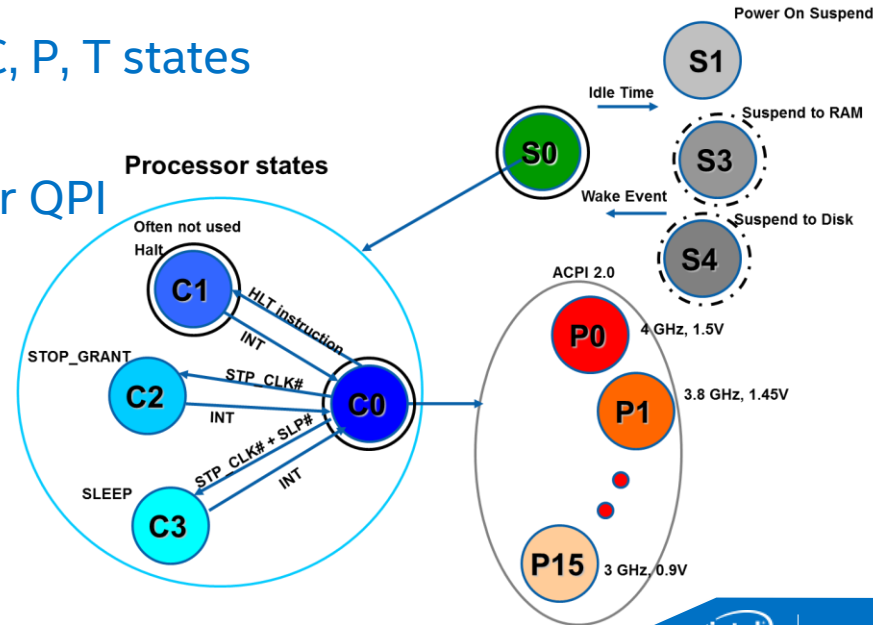
1. Measure Energy into Productive Components with Power Control Unit (PCU) inside Intel processors



Monitors voltage, temperature, power management requests

Controls

- Core/Package C, P, T states
- Memory states
- Power states for QPI



1. Measure Energy into Productive Components: the counters

PACKAGE_POWER_SKU_UNIT (606h): defines units x for time, energy ($\text{unit} = \frac{1}{2^x}$ joule and power

CPU related RAPL counters:

- PACKAGE_ENERGY_STATUS (611h): accumulated energy by the CPU socket
- PACKAGE_POWER_SKU (614h): defines min, max and TDP power of the CPU

DRAM related RAPL counters:

- DRAM_ENERGY_STATUS (619h): to monitor DRAM power consumption
- DRAM_POWER_INFO (61Ch): defines min, max and TDP power of DRAM

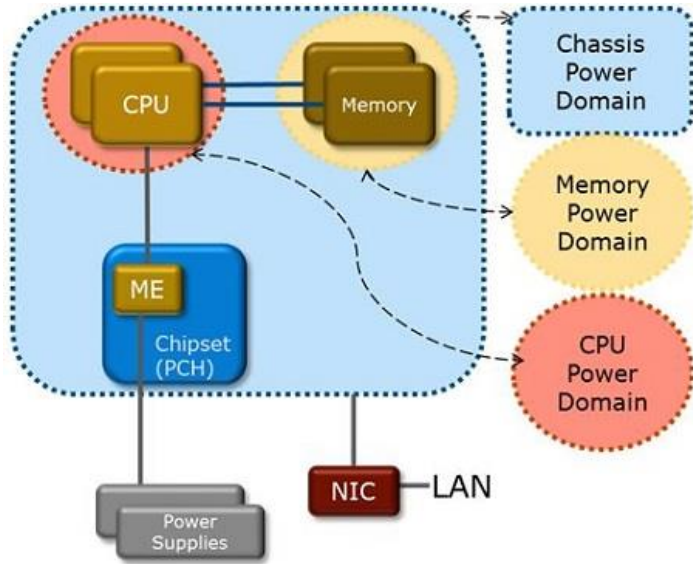
Counters values are updated ~ 1 ms. Require root privileges to read Model Specific Registers

Tools: Intel PCM, turbostat, perf, Likwid, Intel Vtune, and many others:

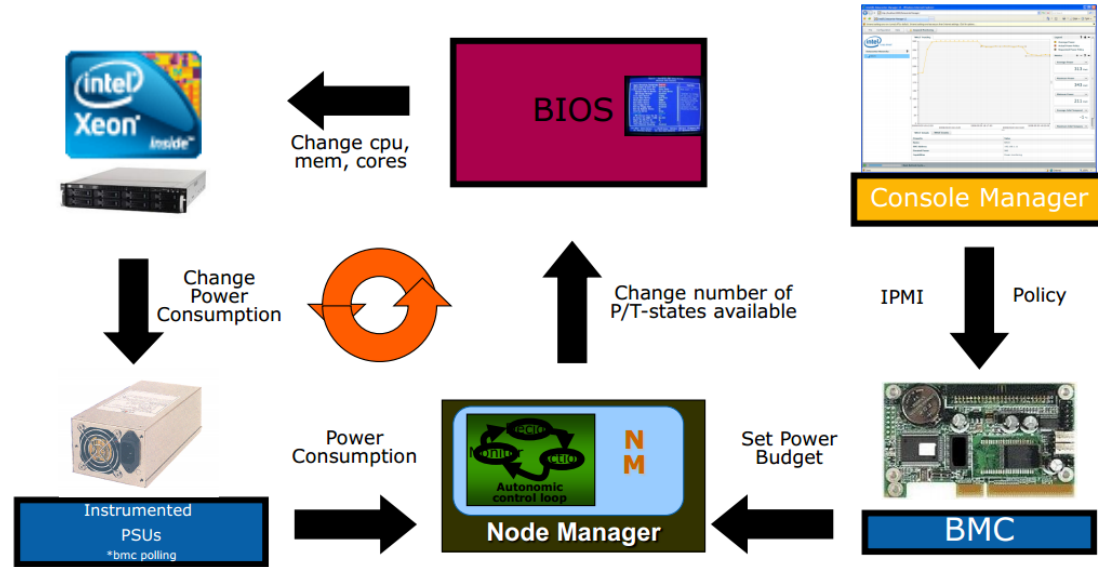
```
# unit=$(echo "ibase=16; 1/2^$(rdmsr -X 0x606 -f 12:8)" |bc -l) // ~1.52*10-5
# counts=`a=$(rdmsr -X 0x611); sleep 1; echo "ibase=16; $(rdmsr -X 0x611)-$a"|bc`
# echo "$counts * $unit" |bc -l // 97.30
```

2. Measure Energy into IT Equipment: servers with Intel Intelligent Power Node Manager

Architecture



Operation



The most recent version added support for Intel Xeon Phi Co-processors (PCIe domain)

2. Measure Energy into IT Equipment: Tools

IPMI Command example*:

- Net function: 2Eh-2Fh, Command: C8h “Get Intel NM Statistics” (see also “Reset NM Statistics”)

```
#!/bin/sh
RET=$(ipmitool -t 0x2c -b 6 raw 0x2e 0xc8 0x57 0x01 0x00 0x01 0x00 0x00)
# RET = 57 01 00 5e 00 53 00 45 02 93 00 f2 c8 01 54 eb 47 02 00 50
if [ "$(echo $RET | cut -c1-8)" = "57 01 00" ]
then
  CUR=`echo $RET | awk '{print "ibase=16;",toupper($4),"+",toupper($5),"*FF"}' | bc`
  MIN=`echo $RET | awk '{print "ibase=16;",toupper($6),"+",toupper($7),"*FF"}' | bc`
  MAX=`echo $RET | awk '{print "ibase=16;",toupper($8),"+",toupper($9),"*FF"}' | bc`
  AVG=`echo $RET | awk '{print "ibase=16;",toupper($10),"+",toupper($11),"*FF"}' | bc`
  echo "CUR:$CUR MIN:$MIN MAX:$MAX AVG:$AVG "          # CUR:94 MIN:83 MAX:579 AVG:147
else
  echo "CUR:NAN MIN:NAN MAX:NAN AVG:NAN"
fi
```

Tools:

- Intel NodeManager Reference Kit (NMRK), Intel DCM, FreeIPMI, may OEM tools (Cisco EnergyWise Suite, Dell OpenManage Power Center, IBM Tivoli Monitoring for Energy Management, etc).

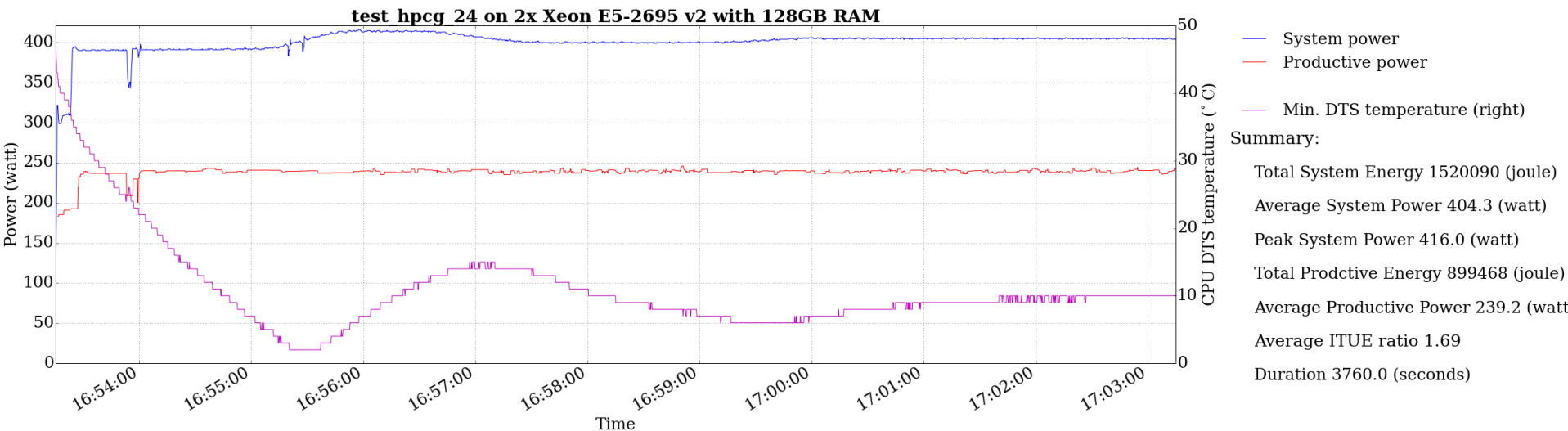
* Source: Intel® Intelligent Power Node Manager 2.0: Specification, Intel DocID: 322999, August 2013

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HPCG: understanding system power behaviour

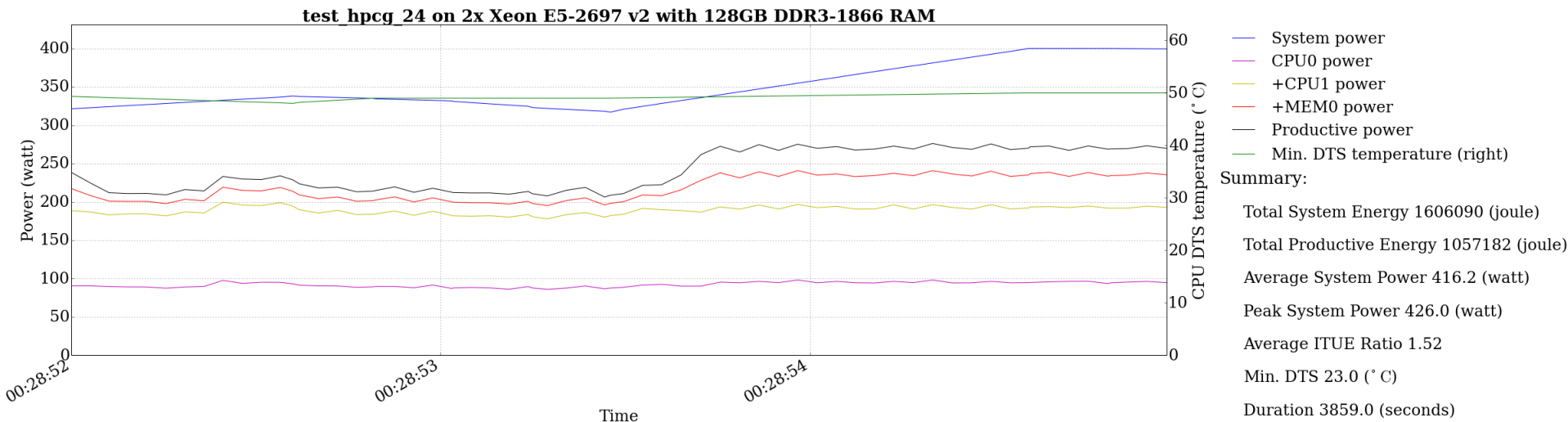
1U chassis, 2c 12 cores, 115W TDP, 128GB RAM DDR3-1600 LV



Quiz: what was happening there?

HPCG: improved system

4U chassis, 2x 12 cores, 130W TDP, 128GB RAM DDR3-1866



Energy and power metering delivered using built-in technologies in Intel platforms

Summary

- Efficiency optimization: new and better metrics should be adopted and used
- Intel delivers technologies for power and energy monitoring and optimization
- Open source and commercial tools are available for community to use RAPL and Intel Power NodeManager

... and one more thing ...

Meet the book of the year... :)

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Foreword by Bronis de Supinski

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Apress
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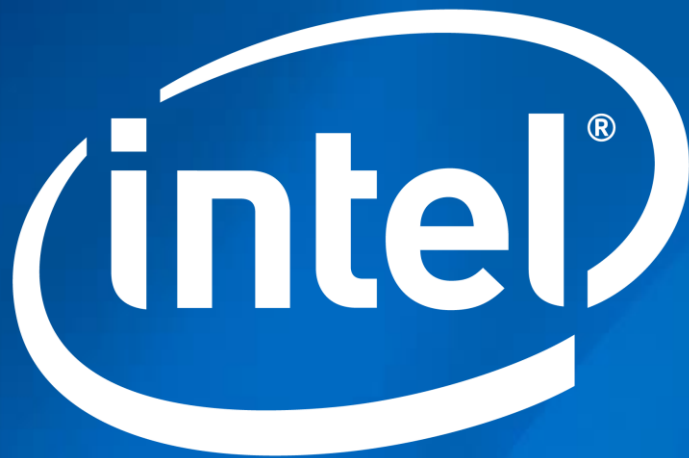


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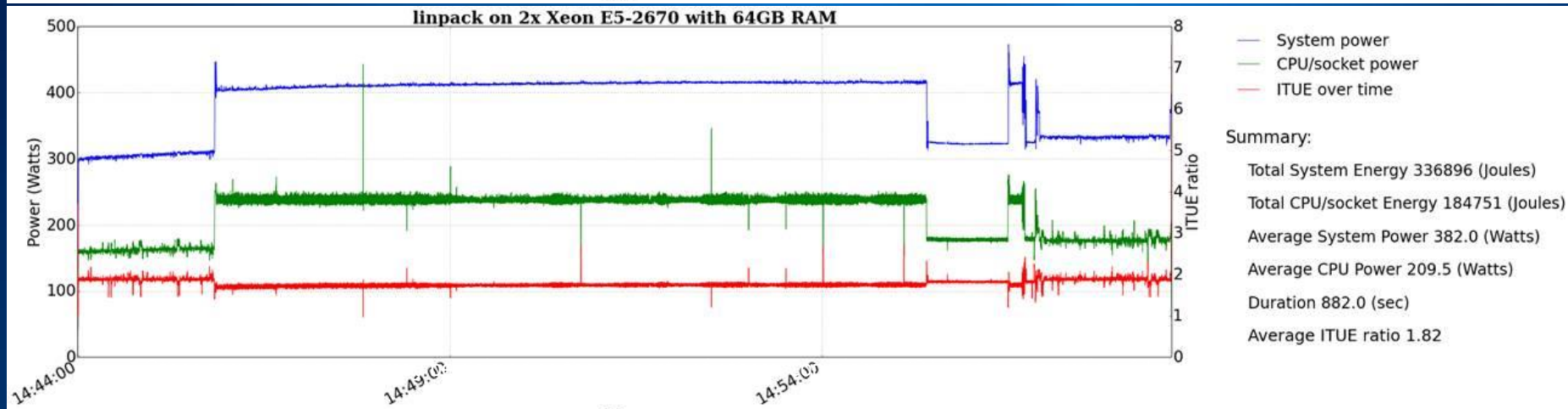
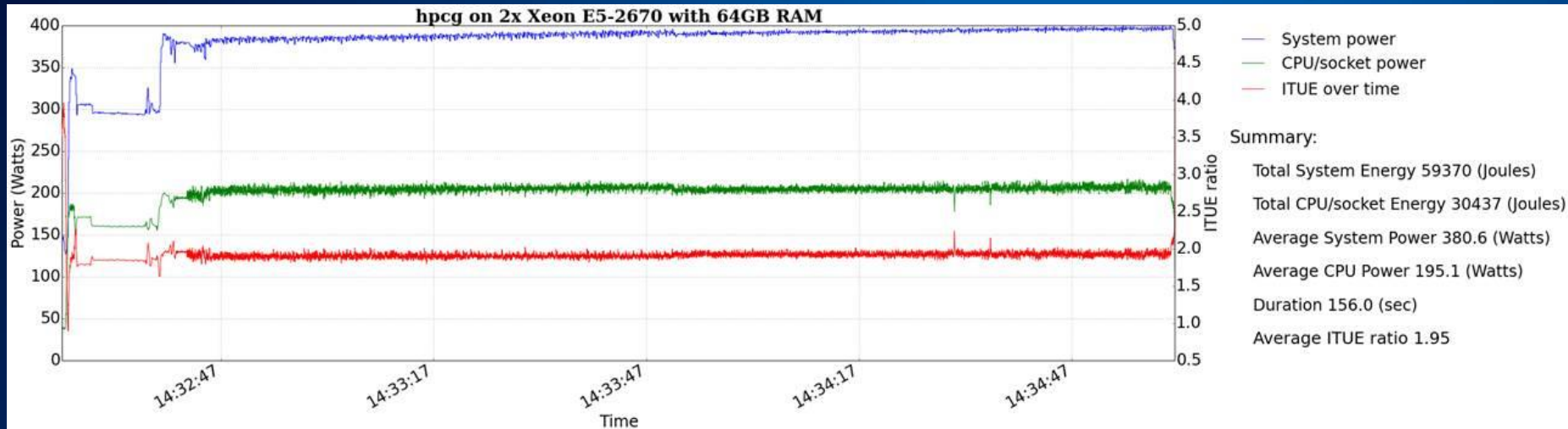
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Observing ITUE: using built-in technologies



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